

## Description

The DGD2005 is a mid-voltage/high-speed gate driver capable of driving N-channel MOSFETs and IGBTs in a half-bridge configuration. High-voltage processing techniques enable the DGD2005's high-side to switch to 200V in a bootstrap operation. The 30ns (maximum) propagation delay matching between the high-side and low-side drivers allows high-frequency switching.

The DGD2005 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with controlling devices. The driver outputs feature high-pulse current buffers designed for minimum driver cross conduction. The low-side gate driver and logic share a common ground.

The DGD2005 is available in a space saving SO-8 (Type TH) package and operates over an extended -40°C to +125°C temperature range.

## Features

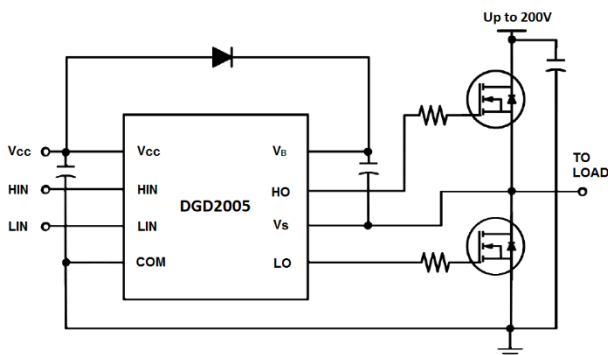
- Floating High-Side Driver in Bootstrap Operation to 200V
- Drives Two N-Channel MOSFETs or IGBTs in Half Bridge Configuration
- Outputs Tolerant to Negative Transients
- Wide Logic and Low-Side Gate Driver Supply Voltage: 10V to 20V
- Logic Input (HIN and LIN) 3.3V Capability
- Schmitt Triggered Logic Inputs with Internal Pull Down
- Delay Matching of 30ns Maximum
- Source/Sink Pulsed Current of 290mA/600mA Typical
- Undervoltage Lockout for Vcc
- Extended Temperature Range: -40°C To +125°C
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

## Applications

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers

## Mechanical Data

- Case: SO-8 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish—Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208
- Weight: 0.075 grams (Approximate)



Typical Configuration



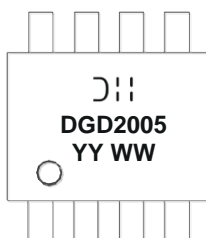
SO-8 (Type TH)  
Top View

## Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DGD2005S8-13	DGD2005	13	12	2500

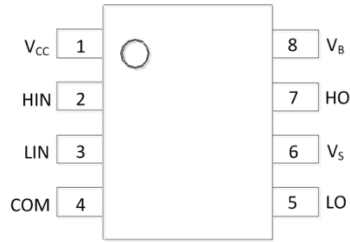
- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3).compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



DII = Manufacturer's Marking  
DGD2005 = Product Type Marking Code  
YY = Year (ex: 18 = 2018)  
WW = Week (01 to 53)

**Pin Diagrams**

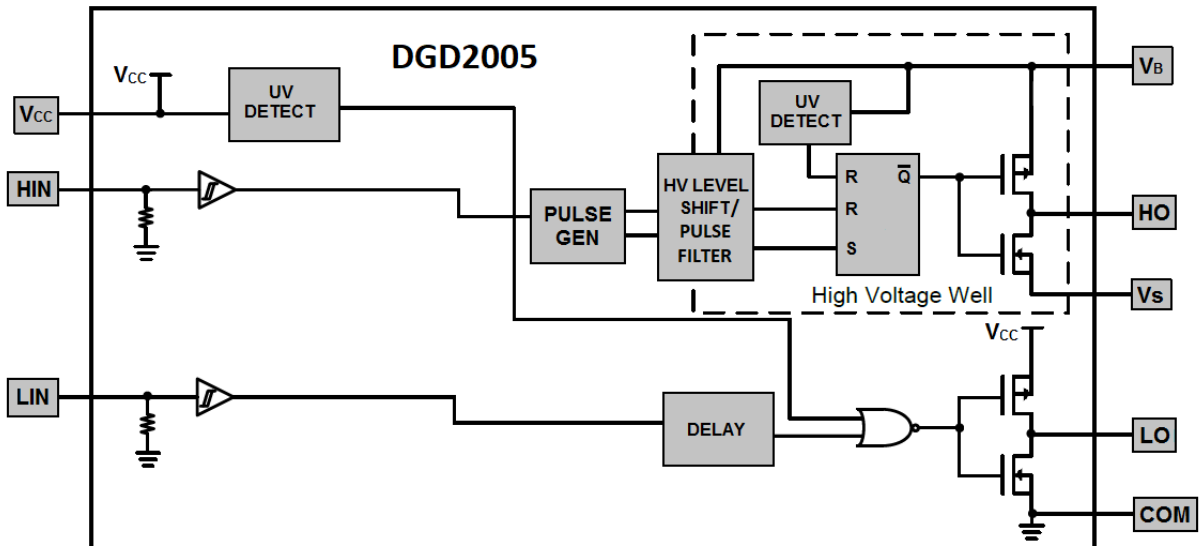


Top View: SO-8 (Type TH)

**Pin Descriptions**

Pin Number	Pin Name	Function
1	V <sub>CC</sub>	Low-Side and Logic Fixed Supply
2	HIN	Logic Input for High-Side Gate Driver Output, in Phase with HO
3	LIN	Logic Input for Low-Side Gate Driver Output, in Phase with LO
4	COM	Low-Side Return
5	LO	Low-Side Gate Drive Output
6	V <sub>S</sub>	High-Side Floating Supply Return
7	HO	High-Side Gate Drive Output
8	V <sub>B</sub>	High-Side Floating Supply

**Functional Block Diagram**



### Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Supply Voltage	V <sub>B</sub>	-0.3 to +224	V
High-Side Floating Supply Offset Voltage	V <sub>S</sub>	V <sub>B</sub> -24 to V <sub>B</sub> +0.3	V
High-Side Floating Output Voltage	V <sub>HO</sub>	V <sub>S</sub> -0.3 to V <sub>B</sub> +0.3	V
Offset Supply Voltage Transient	dV <sub>S</sub> / dt	50	V/ns
Low-Side and Logic Fixed Supply Voltage	V <sub>CC</sub>	-0.3 to +24	V
Low-Side Output Voltage	V <sub>LO</sub>	-0.3 to V <sub>CC</sub> +0.3	V
Logic Input Voltage (HIN and LIN)	V <sub>IN</sub>	-0.3 to V <sub>CC</sub> +0.3	V

### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P <sub>D</sub>	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	200	°C/W
Operating Temperature	T <sub>J</sub>	+150	°C
Lead Temperature (Soldering, 10s)	T <sub>L</sub>	+300	
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

### Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High Side Floating Supply Absolute Voltage	V <sub>B</sub>	V <sub>S</sub> + 10	V <sub>S</sub> + 20	V
High Side Floating Supply Offset Voltage	V <sub>S</sub>	(Note 6)	200	V
High Side Floating Output Voltage	V <sub>HO</sub>	V <sub>S</sub>	V <sub>B</sub>	V
Low Side and Logic Fixed Supply Voltage	V <sub>CC</sub>	10	20	V
Low Side Output Voltage	V <sub>LO</sub>	0	V <sub>CC</sub>	V
Logic Input Voltage	V <sub>IN</sub>	0	5	V
Ambient Temperature	T <sub>A</sub>	-40	+125	°C

Note: 6. Logic operation for V<sub>S</sub> of -5V to +200V.

### DC Electrical Characteristics ( $V_{BIAS}$ ( $V_{CC}$ , $V_{BS}$ ) = 15V, @ $T_A$ = +25°C, unless otherwise specified.) (Note 7)

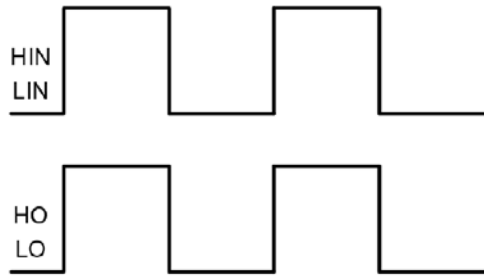
Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Logic "1" Input Voltage	$V_{IH}$	2.5	—	—	V	—
Logic "0" Input Voltage	$V_{IL}$	—	—	0.6	V	—
High Level Output Voltage, $V_{BIAS} - V_O$	$V_{OH}$	—	0.05	0.2	V	$I_O = 2\text{mA}$
Low Level Output Voltage, $V_O$	$V_{OL}$	—	0.02	0.1	V	$I_O = 2\text{mA}$
Offset Supply Leakage Current	$I_{LK}$	—	—	50	$\mu\text{A}$	$V_B = V_S = 200\text{V}$
Quiescent $V_{BS}$ Supply Current	$I_{BSQ}$	20	75	130	$\mu\text{A}$	$V_{IN} = 0\text{V}$ or 5V
Quiescent $V_{CC}$ Supply Current	$I_{CCQ}$	60	120	180	$\mu\text{A}$	$V_{IN} = 0\text{V}$ or 5V
Logic "1" Input Bias Current	$I_{IN+}$	—	5.0	20	$\mu\text{A}$	$V_{IN} = 5\text{V}$
Logic "0" Input Bias Current	$I_{IN-}$	—	—	2.0	$\mu\text{A}$	$V_{IN} = 0\text{V}$
$V_{BS}$ Supply Undervoltage Positive Going Threshold	$V_{BSUV+}$	8.0	8.9	9.8	V	—
$V_{BS}$ Supply Undervoltage Negative Going Threshold	$V_{BSUV-}$	7.4	8.2	9.0	V	—
$V_{CC}$ Supply Undervoltage Positive Going Threshold	$V_{CCUV+}$	8.0	8.9	9.8	V	—
$V_{CC}$ Supply Undervoltage Negative Going Threshold	$V_{CCUV-}$	7.4	8.2	9.0	V	—
Undervoltage Lockout Hysteresis	$V_{UVLOH}$	0.3	0.7	—	V	—
Output High Short Circuit Pulsed Current	$I_{O+}$	130	290	—	mA	$V_O = 0\text{V}$ , $V_{IN} = \text{Logic "1"}$ , $PW \leq 10\mu\text{s}$
Output Low Short Circuit Pulsed Current	$I_{O-}$	270	600	—	mA	$V_O = 15\text{V}$ , $V_{IN} = \text{Logic "0"}$ , $PW \leq 10\mu\text{s}$

Note: 7. The  $V_{IN}$  and  $I_{IN}$  parameters are referenced to COM and are applicable to the two logic pins: HIN and LIN. The  $V_O$  and  $I_O$  parameters are referenced to COM and are applicable to the respective output pins: HO and LO.

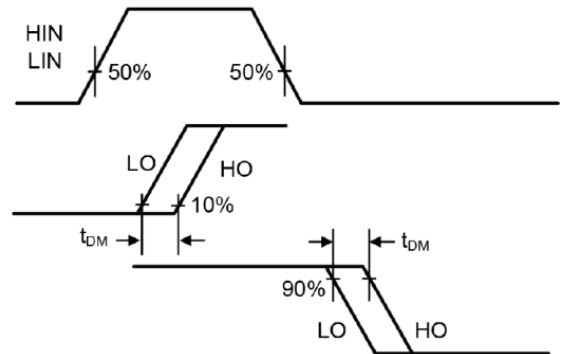
### AC Electrical Characteristics ( $V_{BIAS}$ ( $V_{CC}$ , $V_{BS}$ ) = 15V, $C_L = 1000\text{pF}$ , @ $T_A$ = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Turn-On Propagation Delay	$t_{ON}$	—	220	300	ns	$V_S = 0\text{V}$
Turn-Off Propagation Delay	$t_{OFF}$	—	200	280	ns	$V_S = 0\text{V}$ or 200V
Delay Matching	$t_{DM}$	—	—	30	ns	—
Turn-On Rise Time	$t_R$	—	100	220	ns	$V_S = 0\text{V}$
Turn-Off Fall Time	$t_F$	—	35	80	ns	$V_S = 0\text{V}$

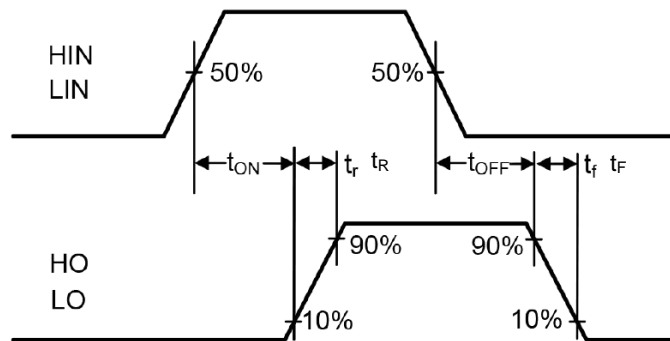
**Timing Waveforms**



**Figure 1.** Input / Output Timing Diagram

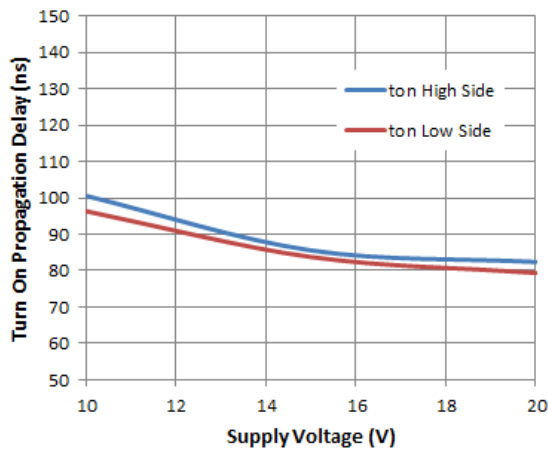


**Figure 2.** Delay Matching Waveform Definitions

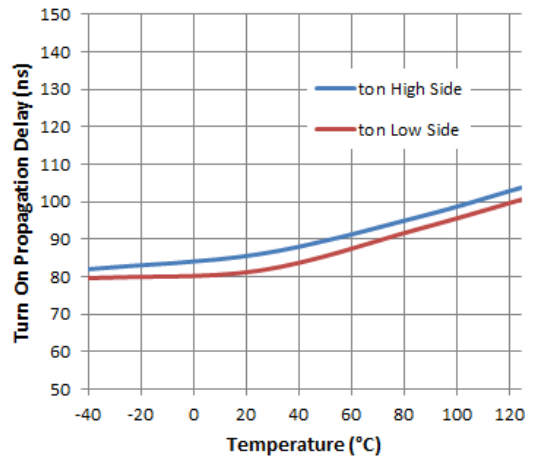


**Figure 3.** Switching Time Waveform Definitions

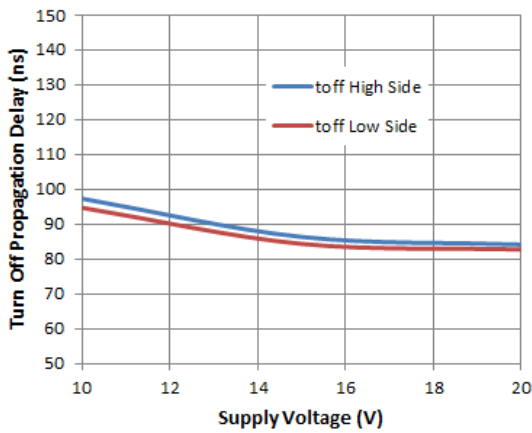
**Typical Performance Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)



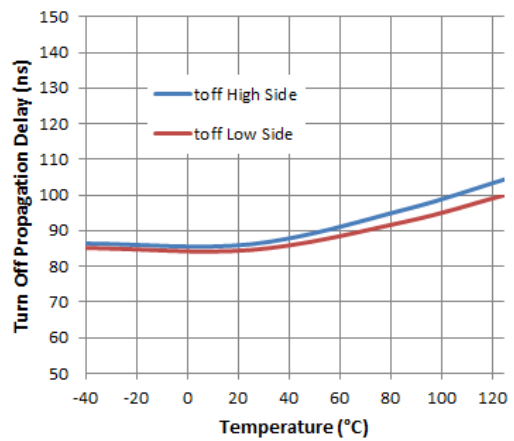
**Figure 4.** Turn-on Propagation Delay vs. Supply Voltage



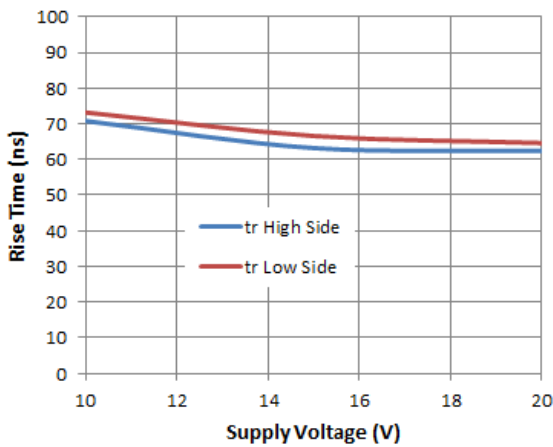
**Figure 5.** Turn-on Propagation Delay vs. Temperature



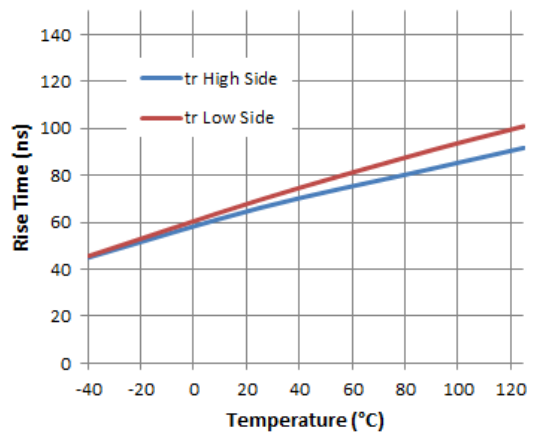
**Figure 6.** Turn-off Propagation Delay vs. Supply Voltage



**Figure 7.** Turn-off Propagation Delay vs. Temperature

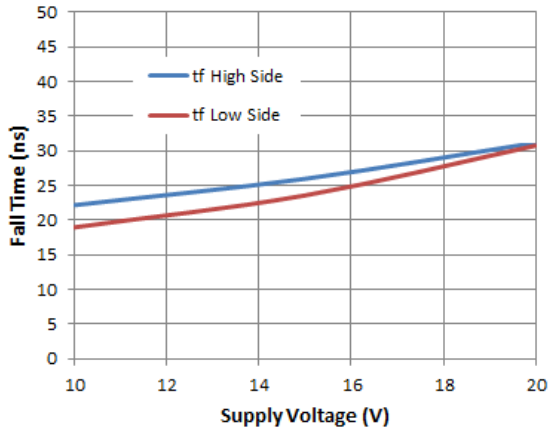


**Figure 8.** Rise Time vs. Supply Voltage

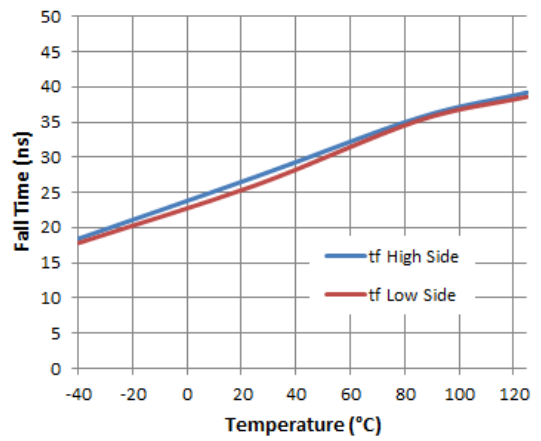


**Figure 9.** Rise Time vs. Temperature

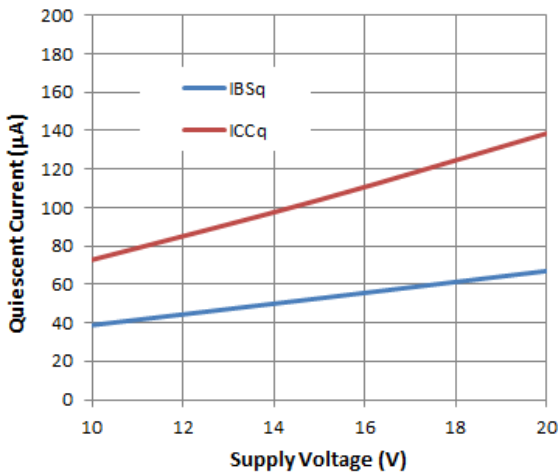
**Typical Performance Characteristics** (continued)



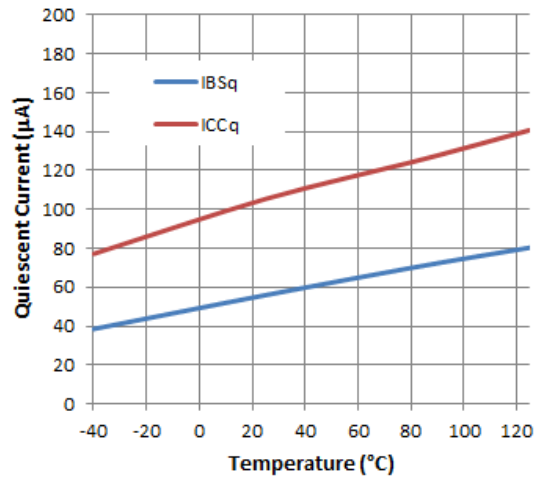
**Figure 10.** Fall Time vs. Supply Voltage



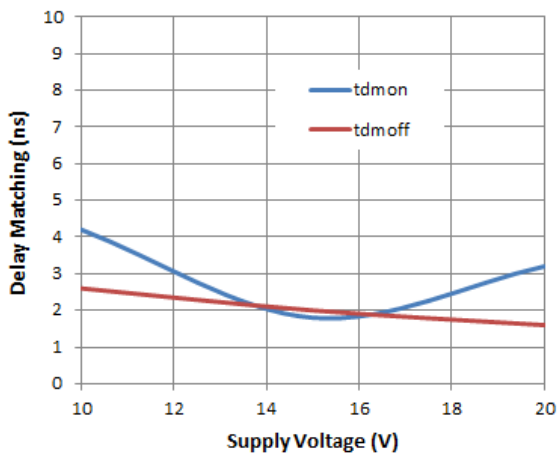
**Figure 11.** Fall Time vs. Temperature



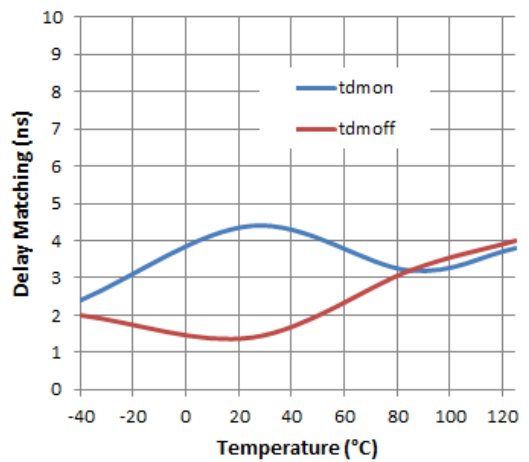
**Figure 12.** Quiescent Current vs. Supply Voltage



**Figure 13.** Quiescent Current vs. Temperature

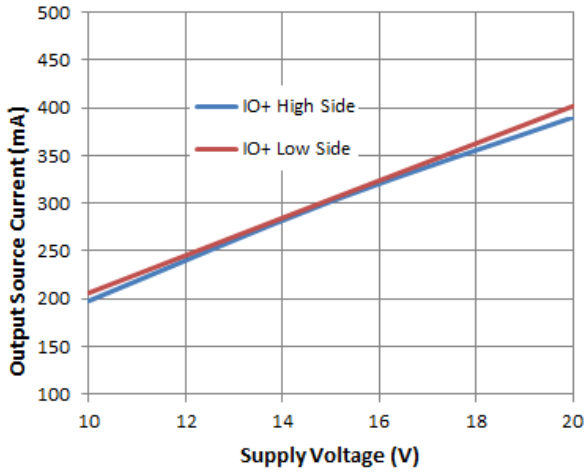


**Figure 14.** Delay Matching vs. Supply Voltage

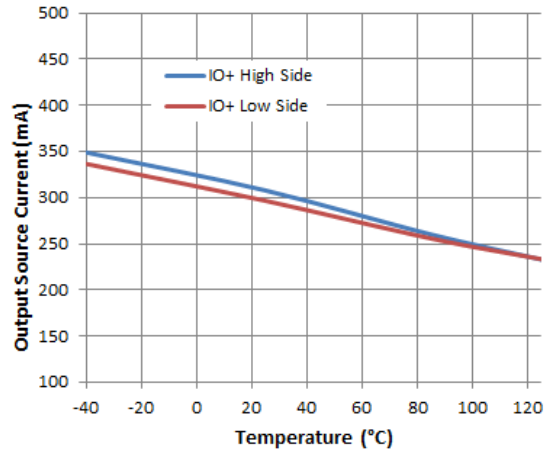


**Figure 15.** Delay Matching vs. Temperature

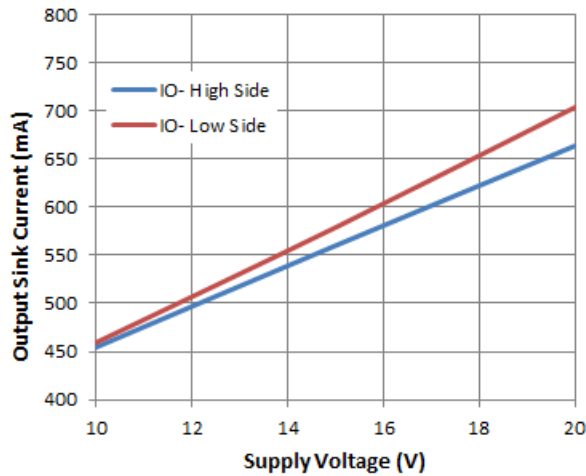
**Typical Performance Characteristics** (continued)



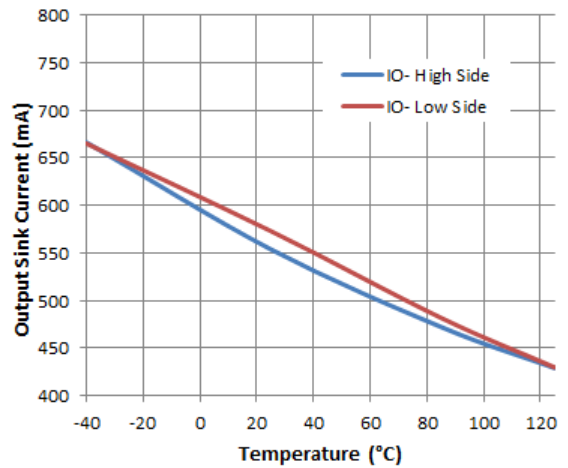
**Figure 16.** Output Source Current vs. Supply Voltage



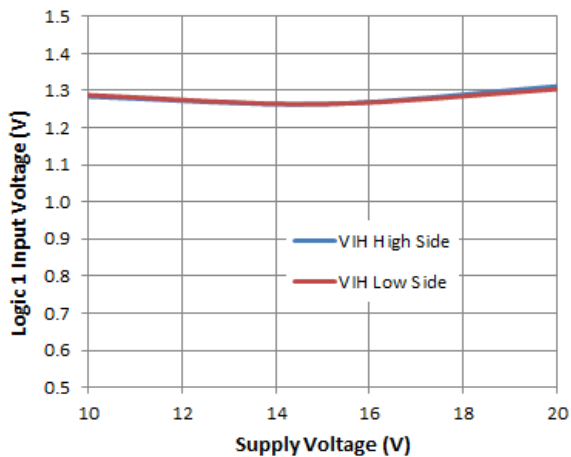
**Figure 17.** Output Source Current vs. Temperature



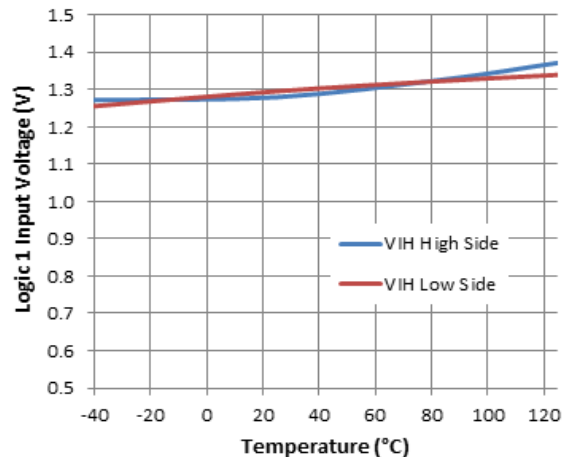
**Figure 18.** Output Sink Current vs. Supply Voltage



**Figure 19.** Output Sink Current vs. Temperature



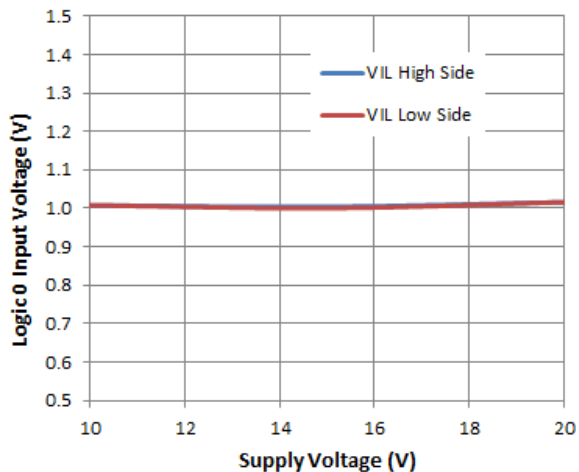
**Figure 20.** Logic 1 Input Voltage vs. Supply Voltage



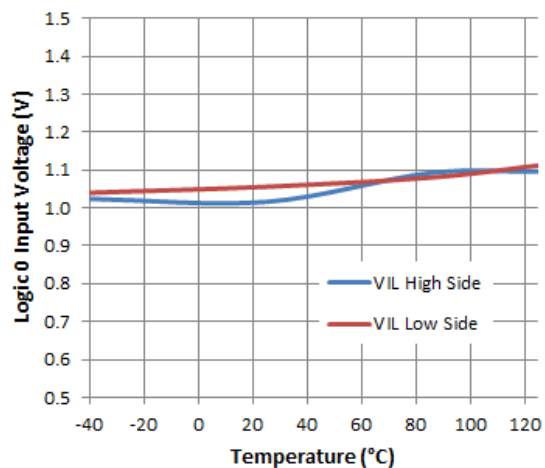
**Figure 21.** Logic 1 Input Voltage vs. Temperature



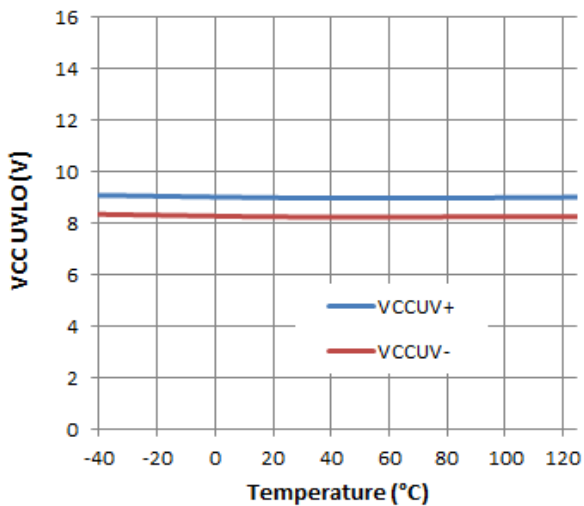
**Typical Performance Characteristics** (continued)



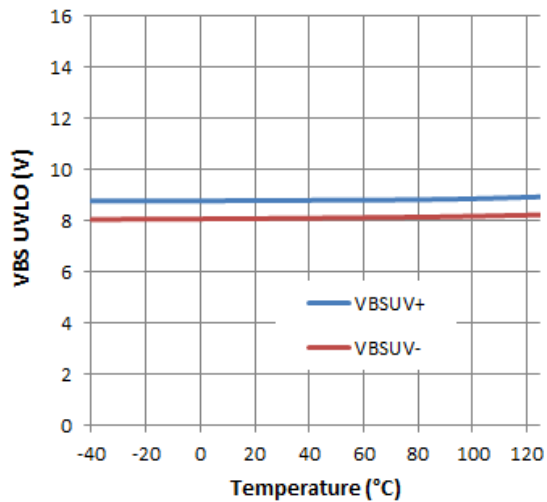
**Figure 22.** Logic 0 Input Voltage vs. Supply Voltage



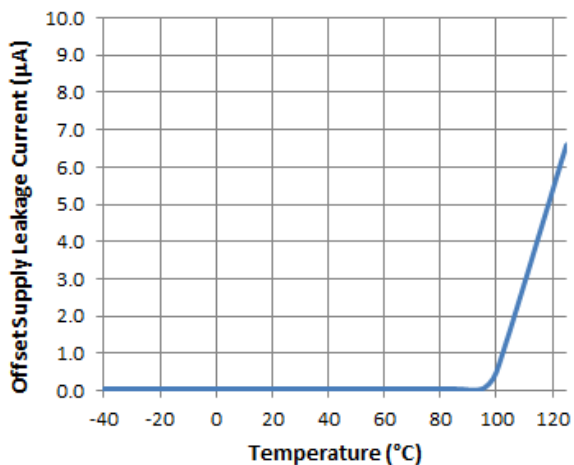
**Figure 23.** Logic 0 Input Voltage vs. Temperature



**Figure 24.** VCC UVLO vs. Temperature



**Figure 25.** VBS UVLO vs. Temperature

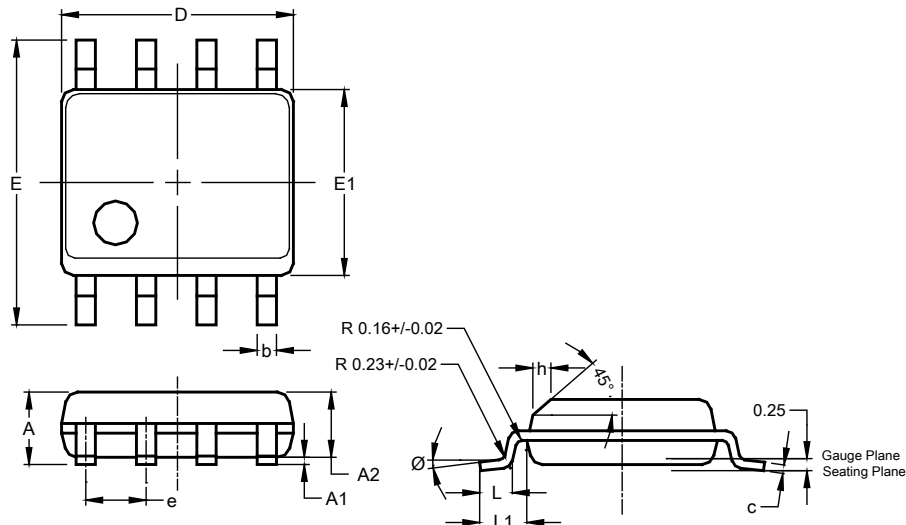


**Figure 26.** Offset Supply Leakage Current vs. Temperature

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

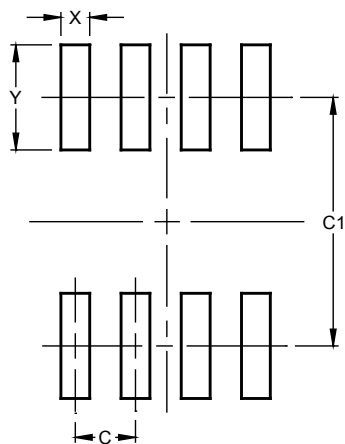
**SO-8 (Type TH)**



**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SO-8 (Type TH)**



Dimensions	Value (in mm)
C	1.27
C1	5.20
X	0.60
Y	2.20

Note: 8. For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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